

FIG 1A

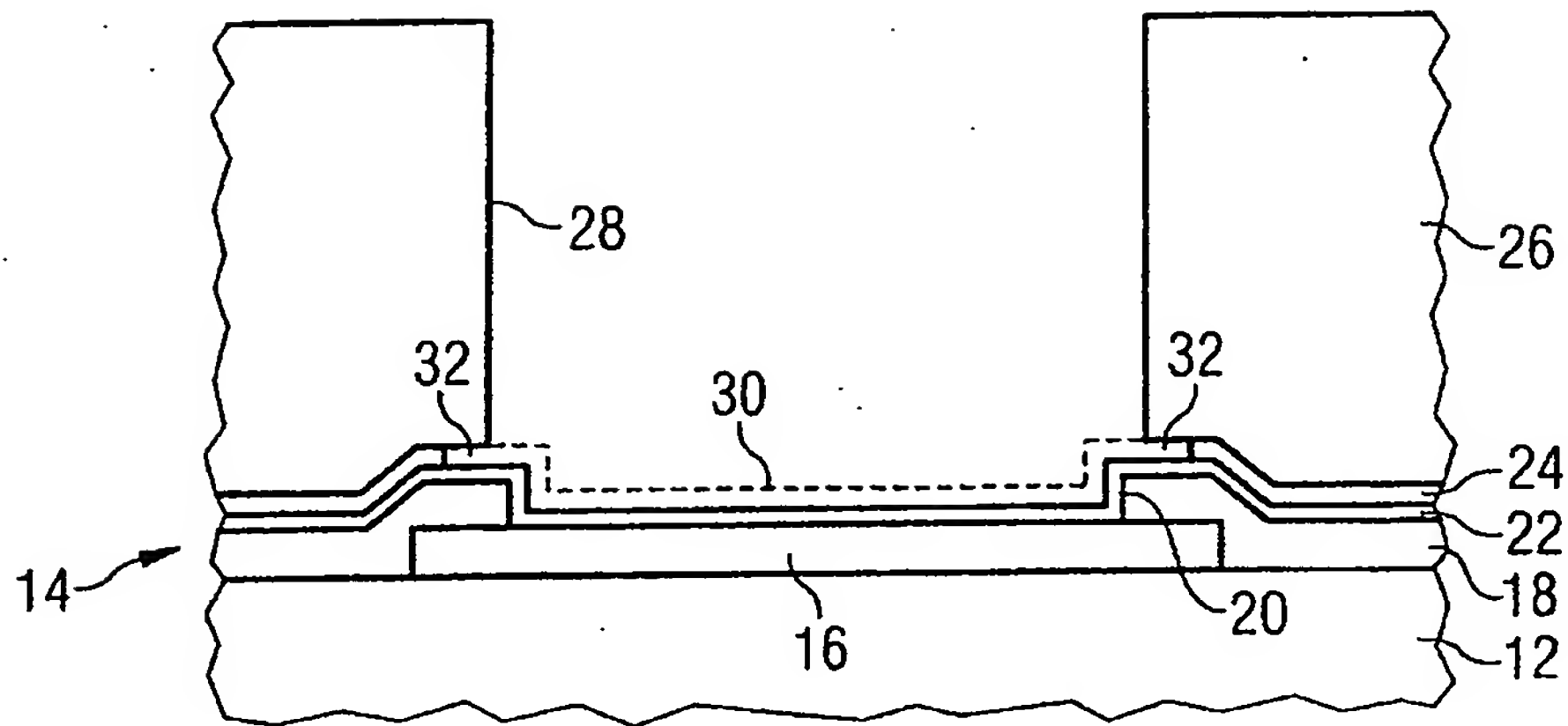


FIG 1B

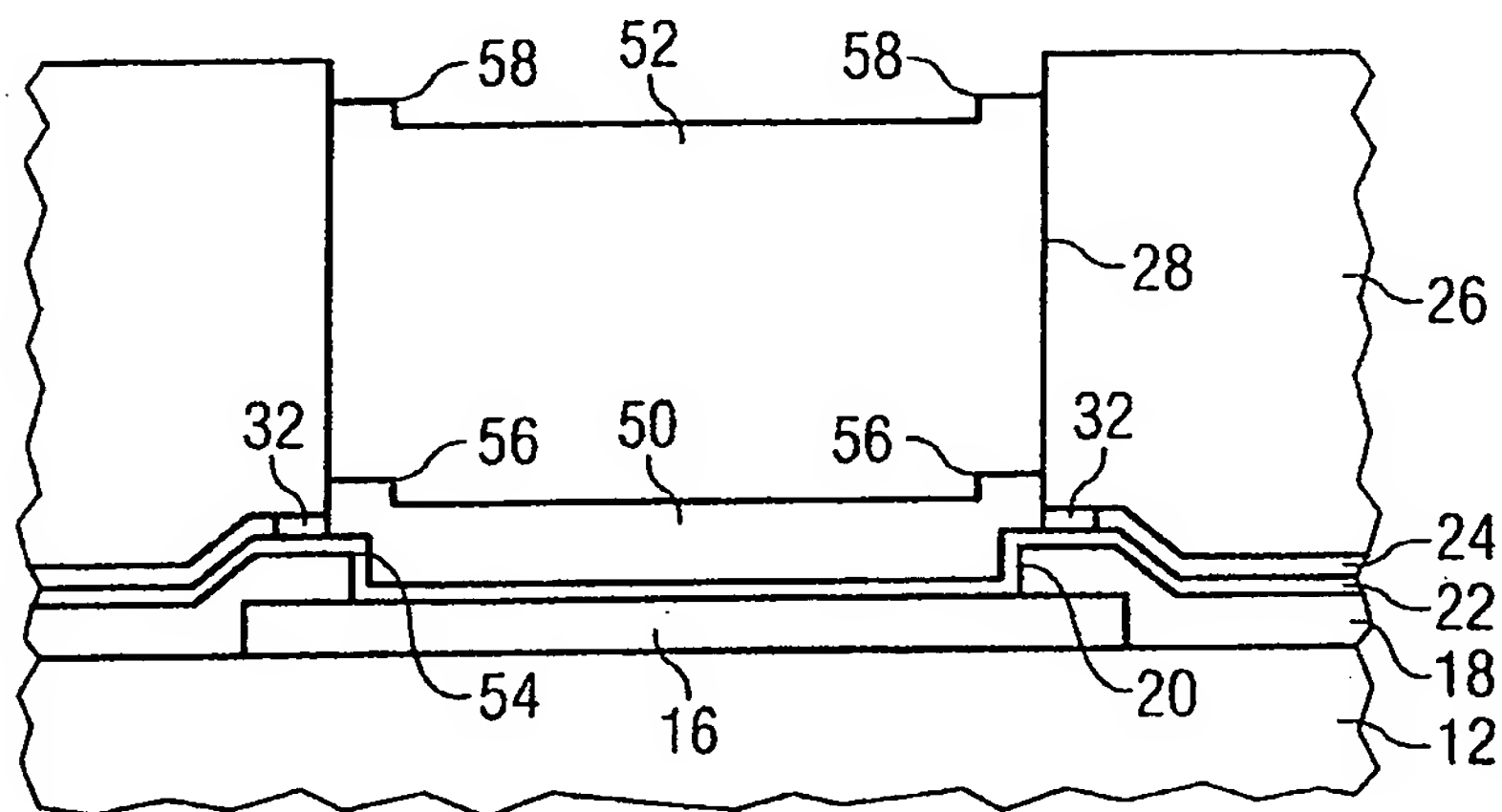
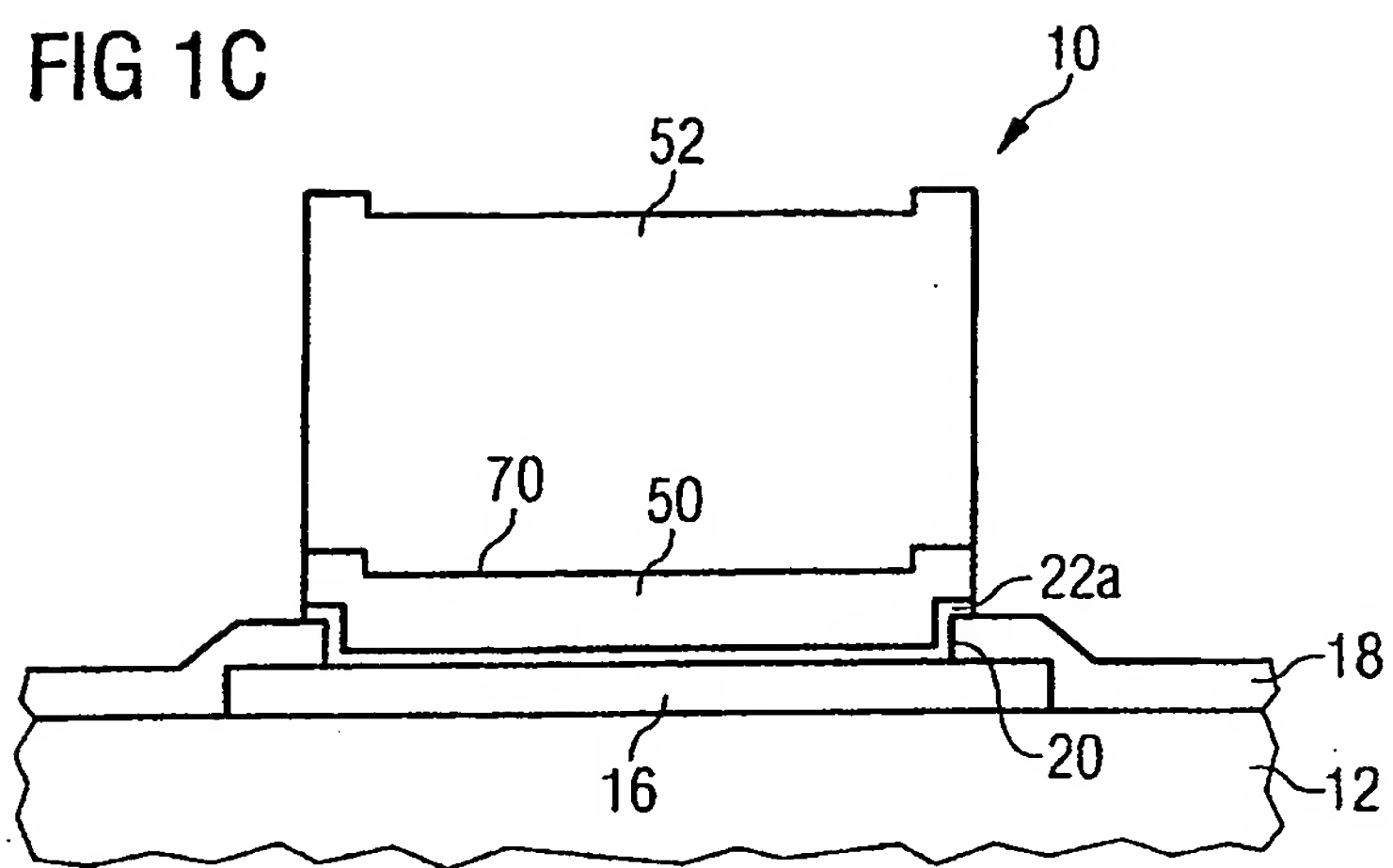


FIG 1C

FIG 1C is a cross-sectional view of a device 10. The device 10 includes a substrate 12, a layer 16, a layer 20, a layer 18, a central structure 50, a layer 70, a layer 52, and a layer 22a.



A cross-sectional view of a microstructure 100. It features a central octagonal core 56, which is surrounded by a layer 50. This layer 50 is further enclosed by a layer 16. The entire structure is surrounded by a layer 22. A horizontal line 28 passes through the center of the octagonal core 56, with a dimension line labeled 'D' indicating its diameter. A horizontal line 80 is shown to the right of the structure, with a dimension line labeled 'B1' indicating its width. The entire structure is surrounded by a material labeled 'Cu' 24.

